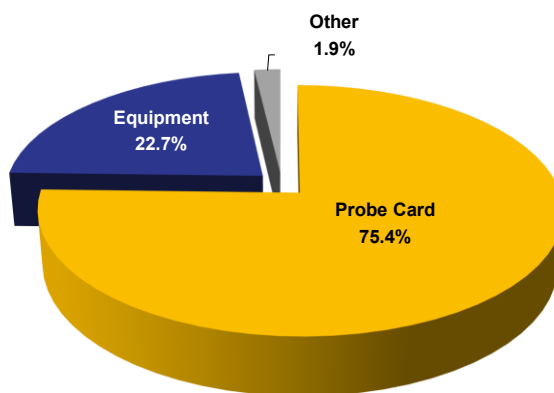


旺矽科技股份有限公司 2025 第二季財報 6223.TT

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1

2025 年產品營收結構



2

合併營收 2025 vs. 2024

NT\$ 000

	2025	2024	YoY
Q1	2,828,698	2,046,692	38.2%
Q2	3,292,785	2,392,994	37.6%
1H	6,121,483	4,439,686	37.9%

損益表 2Q25 vs. 1Q25

NT\$ 000

	2Q25	1Q25	QoQ
Net Revenue	3,292,785	2,828,698	16.4%
Gross profit	1,919,274	1,623,330	18.2%
Income from Operations	1,079,062	840,344	28.4%
Non-op. Income	-322,830	47,380	-781%
Pre-tax Income	756,232	887,724	-14.8%
Net Income	627,916	723,042	-13.1%
EPS	6.67	7.68	-13.1%

損益表 2Q25 vs. 2Q24

NT\$ 000

	2Q25	2Q24	YoY
Net Revenue	3,292,785	2,392,994	37.6%
Gross profit	1,919,274	1,300,045	47.6%
Income from Operations	1,079,062	597,596	80.6%
Non-op. Income	-322,830	86,652	-473%
Pre-tax Income	756,232	684,248	10.5%
Net Income	627,916	542,674	15.7%
EPS	6.67	5.76	15.8%

損益表 1H25 vs. 1H24

NT\$ 000

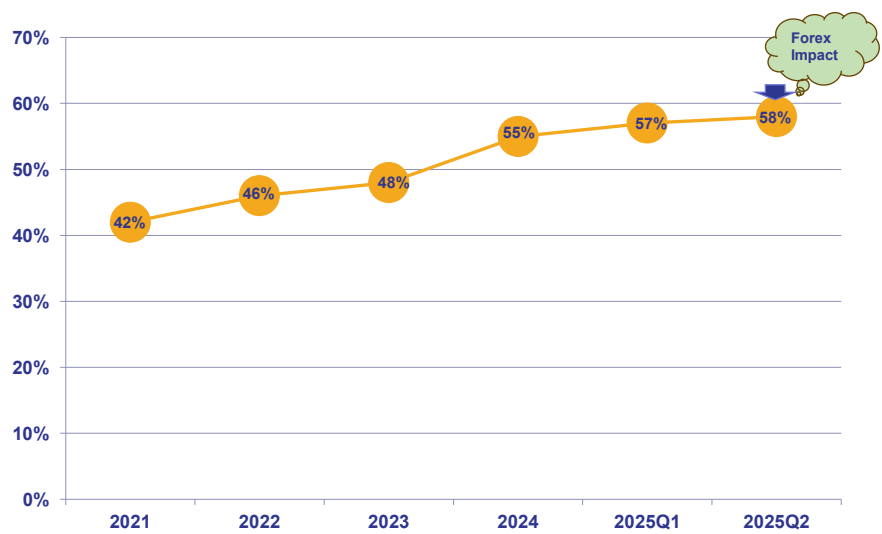
	1H25	1H24	YoY
Net Revenue	6,121,483	4,439,686	37.9%
Gross profit	3,542,604	2,325,937	52.3%
Income from Operations	1,919,406	984,371	95.0%
Non-op. Income	-275,450	182,224	-251%
Pre-tax Income	1,643,956	1,166,615	40.9%
Net Income	1,350,958	935,601	44.4%
EPS	14.35	9.94	44.4%

資產負債表1H25

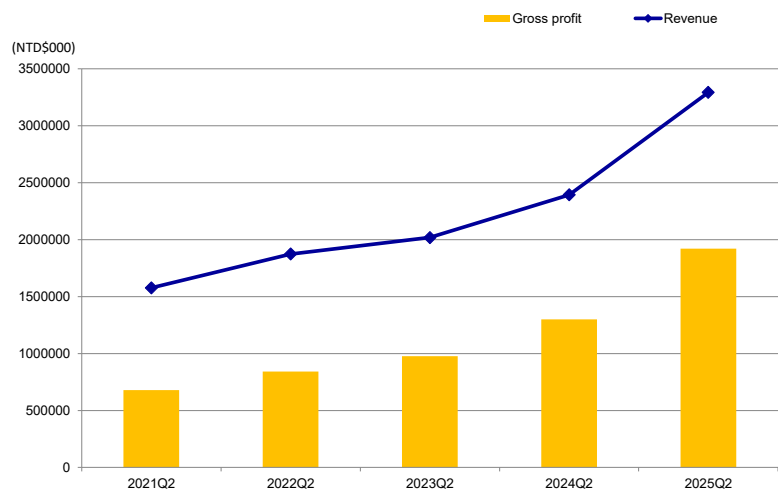
	2025 1H		2024 1H	
				NT\$M
Cash and Cash Equivalents	5,637	28%	2,674	20%
Fixed Assets	8,620	43%	5,913	43%
Total Assets	20,123	100%	13,697	100%
LT Debt	1,152	6%	1,404	10%
Shareholders' Equity	9,393	47%	8,196	60%
EBITDA	1,644	27%	1,166	26%

*EBITDA=operating income + depreciation & amortization expenses

毛利率表現



近五年第二季歷史比較



MPIProbe Card

Advanced Wafer Sort Test Solutions

Vertical / MEMS

Cantilever

Features

Fine Pitch

MEMS

High Pin Count

High Speed

Substrate

Hand-wired

RF

MPI CORPORATION

10

MPI Photonics Automation

Wafer / Device Automated Probe, Test & Measurement, Sort and Inspection

Sensing

- High Power VCSEL Testing
- High Speed VCSEL Testing

Communication

- VCSEL / Photo-Detector Testing
- RF Character
- SiPh Die/PKG Platform

Micro Display

- uLED Mass Production Methodology
- Panel testing platform development

MPI Thermal

Hot and Cold Air Flow
Environmental Temperature Test

-100°C +300°C

ThermalAir Series
Temperature Testing Systems

Applications & Industry Segments

Semiconductor

Automotive

Aerospace

Telecommunications

Fiber Optic

Electronics

Sensors

Advanced Technology

MPI CORPORATION

MPI Advanced Semiconductor Test



Engineering Probe Systems
and
RF Probe Products

50 – 300 mm





26 – 110 GHz



Device Characterization



High Power



RF & mmW



Design Validation



Failure Analysis



Wafer Level Reliability



Silicon Photonics

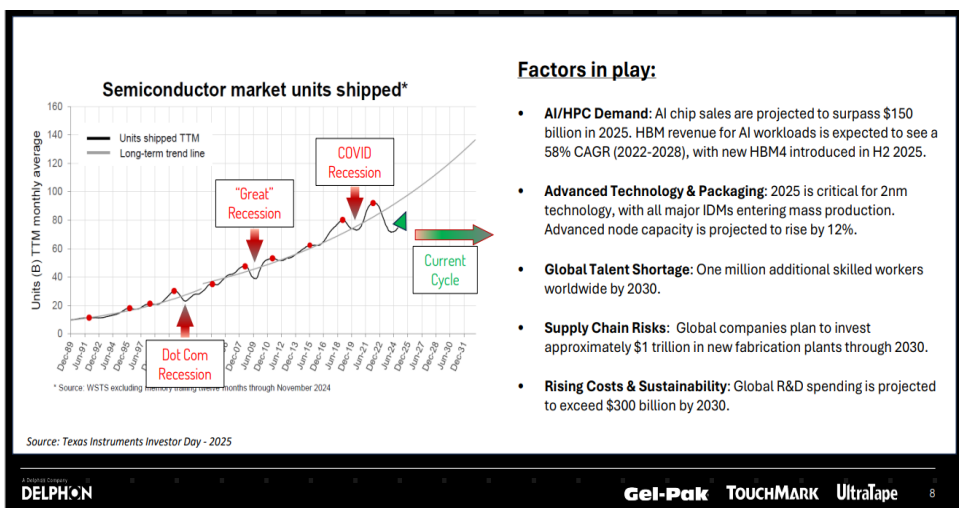


Laser Cutter


13

13

半導體產業具高度週期性



Source: "Increased Value of Wafer Test Innovation" by Jerry Broz, PhD

MPI CORPORATION

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14

14

技術普及加速 | 生成式 AI 興起



Source: N. Shahriari, IEEE ISCCC 2025

Source: J. Song, IEEE ISCCC 2025

DELPHI

Gel-Pak TOUCHMARK UltraTape

12

Source: "Increased Value of Wafer Test Innovation" by Jerry Broz, PhD

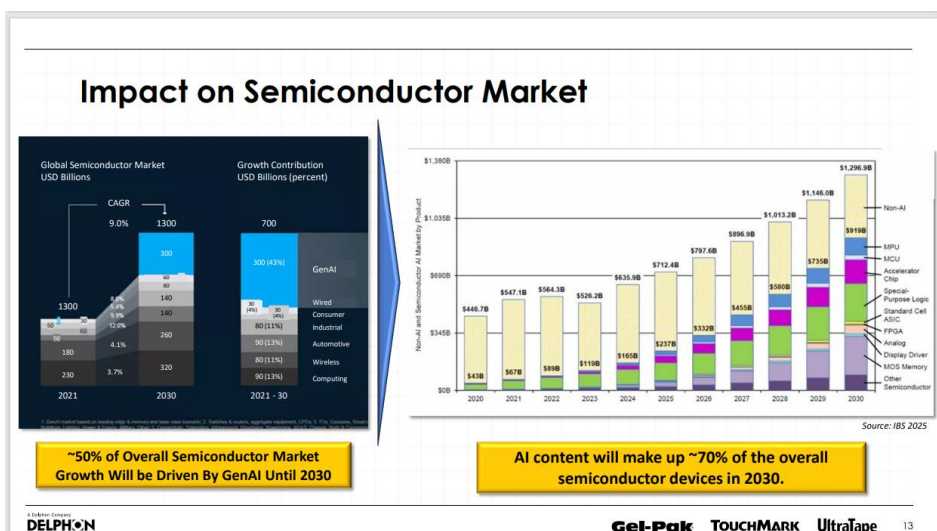
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15

對半導體市場的影響



DELPHI

Gel-Pak TOUCHMARK UltraTape

13

Source: "Increased Value of Wafer Test Innovation" by Jerry Broz, PhD

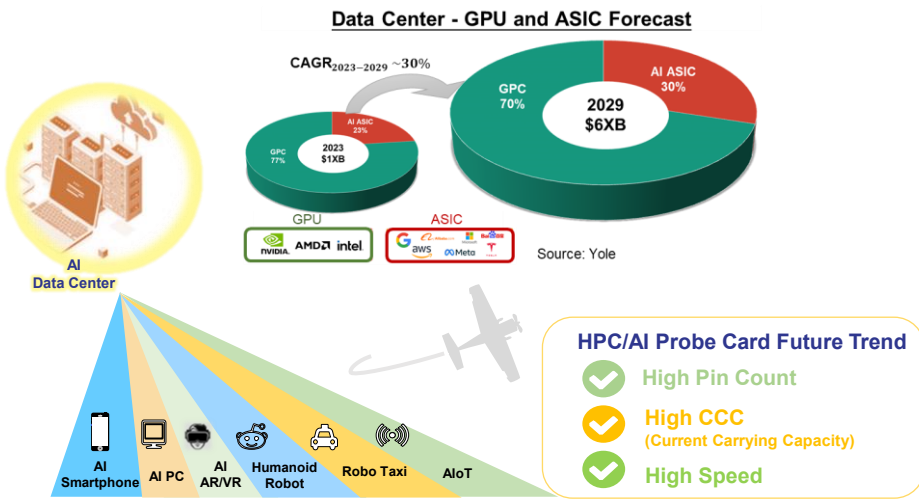
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16

HPC/AI 探針卡挑戰



Source: TSMC

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Thank You

<http://www.mpi-corporation.com>

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